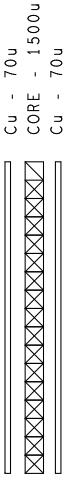


FABRICATION NOTE :

- 1:FABRICATE USING LATEST REVISION OF IPC-6012A CLASS 2 OR ABOVE
- 2:FABRICATE USING MASTER ARTWORK EVSPIN32F0601S1 R1 FOR CIRCUIT PATTERN
NO DEVIATION FROM MASTER ARTWORK ARE PERMITTED WITHOUT WRITTEN APPROVAL FROM AN AUTHORIZED STMicroelectronics REPRESENTATIVE
- 3:VENDOR MUST BE UL QUALIFIED AND BOARDS MUST BE IDENTIFIED WITH APPROPRIATE VENDOR UL IDENTIFICATION MARK, LOT OR JOB NUMBER AND PCB MATERIAL FLAMMABILITY RATING (94V-0) MINIMUM
- 4-MATERIAL: FR4 ROHS COMPLIANT MINIMUM 170 G (High TG)
SEE "DETAIL 'A'" FOR BOARD THICKNESS, COPPER WEIGHT AND LAYER CONSTRUCTION
- 5:GREENE SOLDER MASK BOTH SIDE OF BOARD WITH LIQUID PHOTO IMAGEABLE SOLDERMASK
- 6:FINISH: HAL Lead Free
- 7:FOR SMT COMPONENTS WITH PIN PITCH OF 0.019 INCH OR MORE NO GANG RELIEF OF SOLDER MASK IS ALLOWED
- 8:SILKSCREEN TO BE WHITE, NON CONDUCTIVE, EPOXY INK OR EQUIVALENT
- 9:THIS IS NOT A CONTROLLED IMPEDANCE BOARD
(MEANS OF MATERIAL TYPE INDICATED ON THE YELLOW CARD DOCUMENT)
- 11:VENDOR TO PROVIDE BOARD STACK-UP FOR IMPEDANCE APPROVAL PRIOR TO BOARD FABBRICATION-STACK UP AND IMPEDANCE TO INCLUDE COPPER PLATING ON OUTER LAYERS,FAB DRAWING STACK-UP DIMENSION ARE PROVIDED FOR REFERENCE ONLY
VENDOR TO PROVIDE BOARD FOR IMPEDANCE TEST RESULTS AND COUPON
- 12:TEARDROPPING OF VIAS AND PADS ALLOWED AT PAD TO TRACE INTERSECTION TO INSURE A 2MIL ANULAR RING AT THE JUNCTION
- 13:REMOVE SILKSCREEN FROM SOLDERABLE SURFACE
- 14:ALL BOARD TO BE 100% ELECTRICALLY NETLIST TESTED FOR OPENS AND ON SHORTS, APPLY TEST STAMP IN REFERENCED AREA
- 15:THIS BOARD SHALL BE FULLY COMPLIANT WITH UL796

DETAIL 'A'

LAYER BUILD UP
(reference only)



(external Cu th are after plating)
estimated total thickness 1650u

| SLOT HOLES: TOP to BOTTOM | | | |
|---------------------------|---------------|----------|--------------|
| ALL UNITS ARE IN MILS | | | |
| FIGURE | FINISHED SIZE | ROTATION | PLATED QTY |
| | 787.4x43.3 | 90.000 | NON-PLATED 4 |

| DRILL CHART: TOP to BOTTOM | | | |
|----------------------------|---------------|----------|--------------|
| ALL UNITS ARE IN MILS | | | |
| FIGURE | FINISHED SIZE | ROTATION | PLATED QTY |
| A | 12.0 | - | PLATED 546 |
| B | 31.5 | - | PLATED 16 |
| C | 35.43 | - | PLATED 34 |
| D | 43.31 | - | PLATED 6 |
| E | 47.24 | - | PLATED 8 |
| F | 51.0 | - | PLATED 2 |
| G | 55.0 | - | PLATED 5 |
| H | 59.05 | - | PLATED 4 |
| I | 82.68 | - | PLATED 2 |
| L | 35.43 | - | NON-PLATED 2 |
| M | 125.98 | - | NON-PLATED 6 |

| Finished Hole Tolerance - - All units are in Inches - | | | |
|--|-------------------------------------|---|--|
| Finish Hole Diameter | Plated Through Finish Hole Diameter | Non Plated Through Finish Hole Diameter | |
| 0.008"-0.013" | +0.002/-FH5" | +/-0.002" | |
| 0.014"-0.063" | +/-0.003" | +/-0.002" | |
| 0.064"-0.156" | +/-0.004" | +/-0.003" | |
| 0.157"-0.250" | +/-0.007" | +/-0.004" | |
| 0.251"and up | +/-0.007" | +/-0.005" | |
| 0.125" | Non Plated Only | +0.003/-0.000" | |

| REVISION DATE | Description | | Symbol |
|---|---------------------------------|-----------------------------|---------------------------------|
| | DRILLING AND PROFILING | | STSPIN32F0601Q |
| | I&PC, AMS Group AGRATE B. ITALY | | Group EVSPIN32F06Q1S1 |
| ALL RIGHTS STRICTLY RESERVED. REPRODUCTION OR ISSUE TO THIRD PARTIES IN ANY FORM WHATEVER IS NOT PERMITTED WITHOUT WRITTEN AUTHORIZATION FROM STMicroelectronics. | | ISO | SCALE: 1 : 1 |
| TOLERANCE UNLESS NOTED | | UNIT=MM | REV. 1.0 |
| linear | | 0 >10 <10 >50 <200 | ANG. LES. |
| midle | | ±0.1 ±0.2 ±0.3 ±0.5 ±1° | Material |
| accurate | | ±0.05 ±0.1 ±0.15 ±0.25 ±30° | Treatment and surface finishing |
| Drawn | RIGO M. | date 11-June-2020 | |
| Approved | | date | |